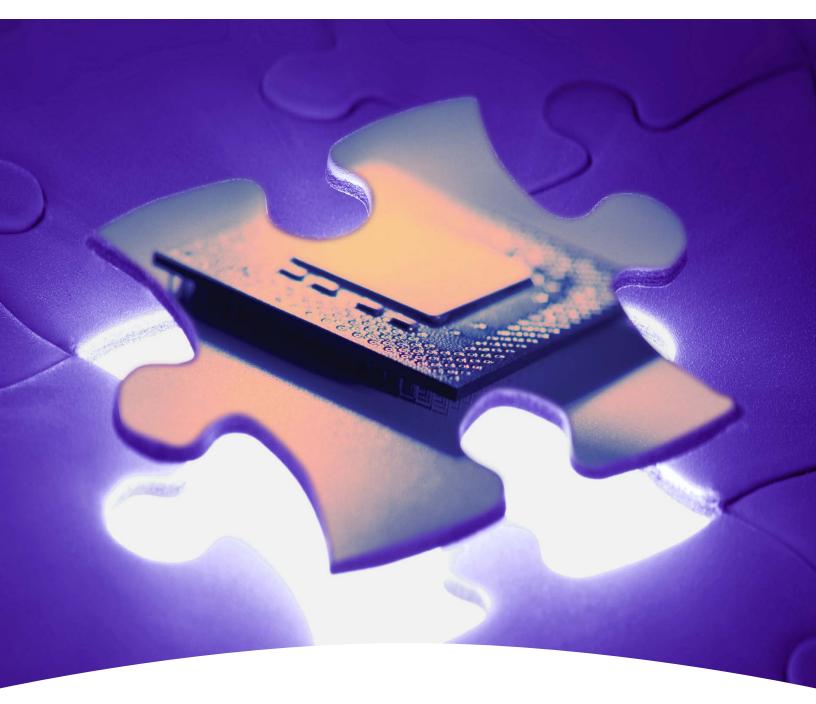
Honeywell



Honeywell PTM5000/PTM5000-SP Phase Change Thermal Interface Materials

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HIGH THERMAL CONDUCTIVITY
PHASE CHANGE MATERIAL IN
PAD AND PASTE FORMATS

BENEFITS

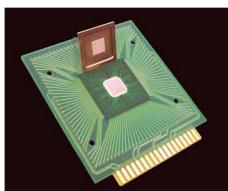
- High performance filler and polymer technology
- Phase change at 45°C
- Highly conductive filler with tailored loading to optimize performance
- · Superior handling and reworkability
- Reliable thermal performance

FEATURES

 Key outputs in thermal impedance for the PTM5000 Series have been measured to fit individual needs.

OVERVIEW

Honeywell's PTM5000 Series, a highly thermally conductive Phase Change Material (PCM) in both pad and dispense formats, is designed to minimize thermal resistance at interfaces, maintain excellent performance through reliability testing, and provide scalable application at a competitive cost. Based on a novel polymer PCM system, this material exhibits excellent wetting at interfaces during typical operating temperature ranges, resulting in very low surface contact resistance.



A proprietary filler material provides high thermal conductivity (4.4 W/m·K) and low thermal impedance (<0.16°Ccm²/W @ 2 mil), making the PTM5000 Series desirable for high performance integrated circuit devices.

APPLICATIONS

Clamping pressure and temperature are suggested to achieve a minimum bond line thickness of the thermal interface material, typically less than 1.5 mil (0.038mm) for best performance. The material must go through the phase change temperature in order to exhibit entitlement performance.



PTM5000 Series Thermal Impedance ASTM D-5470										
c 0.35										
0.30 0.25 0.25 0.20 0.15 0.10 0.10 0.05 0.05										
ပ္ညီ 0.25		PT	M5000 S	eries						
0.20		k	= 4.4 W/ı	n-K						
0.15			/							
<u>E</u> 0.10		/					_			
0.05	/									
F 0.00	20	40	60	80	100	120	140			
Bond Line Thickness (µm)										

Physical Properties	Unit	Test Method	PTM5000	PTM5000-SP
Thermal Conductivity	W/m·K	ASTM D5470	4.4	4.4
Thermal Impedance @ no shim	°C·cm²/W	ASTM D5470 Modified	0.07	0.07
Thermal Impedance @ 50µm	°C·cm²/W	ASTM D5470 Modified	0.14	0.14
Specific Gravity	g/cm ³	ASTM D374	2.3	2.0
Viscosity	Pa·s @2s⁻¹, 25°C	Rehometer HON	NA	82
Volume Resistivity	Ω·cm	ASTM D257-700	2.1x10 ¹⁴	2.1x10 ¹⁴
Thickness Range	mm		0.20-1.00	NA

Shelf Life

Storage Condition 19-24°C, <65%RH

12 Months

Thermal Impedance Post Reliability (ASTM E1461)

End of Line 0.10°C-cm²/W
Temperature Cycling "B" 0.07°C-cm²/W

(-55°C to 125°C, 1000 cycles)

 Bake 125°C, 1000 h
 0.08°C-cm²/W

 Bake 150°C, 1000 h
 0.07°C-cm²/W

 HAST, 96 h
 0.09°C-cm²/W

 85°C, 85% RH, 1000 h
 0.11°C-cm²/W



Honeywell Electronic Materials

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